

ITherm 2017

ITherm 2017: Sixteenth Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems

May 30 – June 2, 2017

Walt Disney World Swan & Dolphin Hotel
Lake Buena Vista (Orlando), FL USA

ITherm 2017 is the leading international conference for scientific and engineering exploration of thermal, thermo-mechanical and emerging technology issues associated with electronic devices, packages, and systems. ITherm 2017 will be held along with the 67th Electronic Components and Technology Conference (ECTC 2017, www.ectc.net), a premier electronic packaging conference, at the Disney World Resort. Joint registrations are available at a discounted rate. All papers will be peer reviewed by two or more reviewers, and will be published in the ITherm proceedings. Selected papers will be published in a special issue of Journal of Electronics Packaging. All papers will be presented in oral sessions. Students have the opportunity to apply for ITherm travel grants and make an oral presentation and also participate in poster presentation of their paper and compete for poster awards. In addition to paper presentations and vendor exhibits, ITherm 2017 will have panel discussions, keynote lectures by prominent speakers, and professional short courses. Original papers are solicited in the following general areas of interest (but not limited to):

Thermal-1 Component Level -- Track I

- Single/Multi-Chip Module, System in Package
- 3D Packaging, Embedded Cooling
- Heat Pipes, Vapor Chambers, Thermosyphons
- Heat Spreaders
- Hot Spot Cooling
- Thermoelectric
- Single & Two-Phase Cold Plates
- Pumps, Fans
- Heat Exchangers, Air Cooling

Thermal-2 System Level -- Track II

- Data Center, Energy Efficiency
- Thermal Storage
- Immersion Cooling, Refrigeration
- Mobile, Internet of Things, MEMS
- Telecommunication Systems
- Automotive
- Space and Aerospace
- Power Electronics
- LEDs
- Photovoltaics
- RF Electronics
- Battery

Mechanics & Reliability -- Track III

- Thermo-mechanical Modeling and Simulation of Devices, Components, Boards, and Systems
- Mechanics and Reliability of Solder Joints & Interconnects
- Materials Characterization, Processing, Constitutive Models
- Failure Mechanics, Fatigue, Damage Modeling
- Experimental Techniques for Packaging Deformations, Strains, and Stresses
- Shock, Drop, and Vibrational Analysis of Packages, Sub-Systems, and Systems
- TSV / 3D Reliability and Packaging Challenges
- Mechanics issues in Assembly and Manufacturing

Emerging Technologies & Fundamentals -- Track IV

- Numerical Methods from Nano-to-Macro Scale
- Experimental Methods from Nano-to-Macro Scale
- Nanotechnology incl. 1&2-Dimensional Materials
- Thermal Interface Materials, Phase Change Materials
- Embedded Cooling
- Transistor Technology
- Novel Materials and Manufacturing Techniques
- Measurement and Instrumentation Techniques
- Prognostic Health Management and Reliability Analysis

Some important dates: **Extended to**
Deadline for Abstracts: **Sept. 16, 2016**
Notification of Acceptance: Sept. 30, 2016
Draft Paper Submission: Dec. 20, 2016
Reviews Returned: Feb. 6, 2017
Final Paper Submission: Mar. 13, 2017

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